

Pre-Injector Overview & Goals

C.Y. Tan
17 Mar 2010

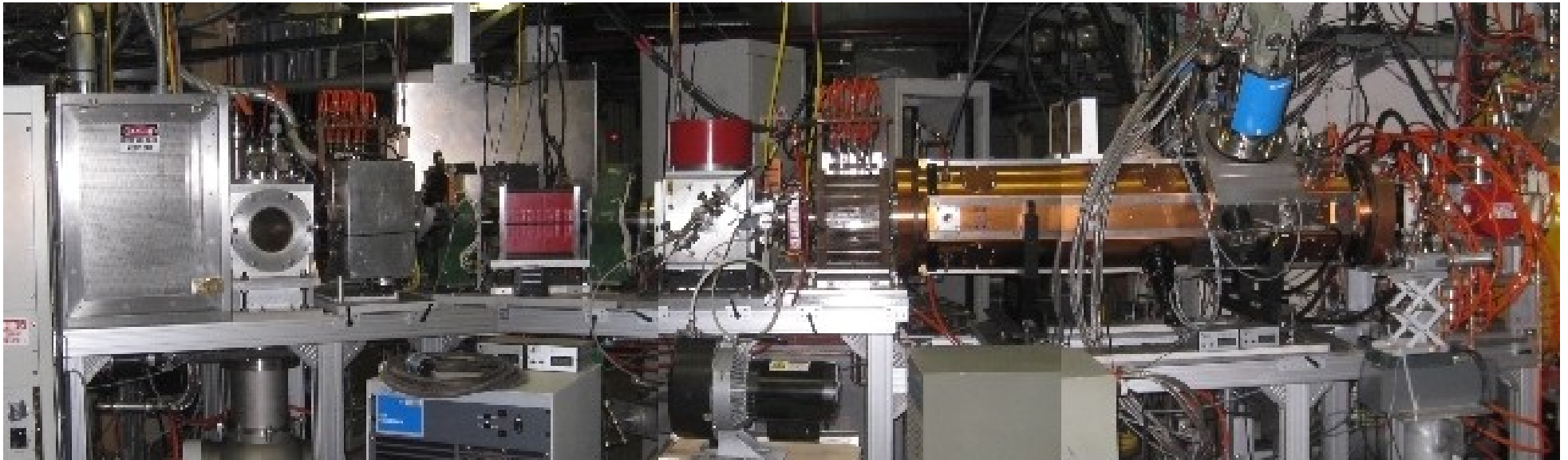
Overview

- How the new pre-injector looks like
 - Round Source
 - LEBT
 - RFQ
 - MEBT
- Work that is ongoing
 - Round source (Bollinger)
 - Chopper (Bollinger, Tan, Lackey, Markarov)
 - Solenoids, quads (Markarov, Kashikin, Velev)
 - RFQ (outside vendor, req is approved, being bought)
 - Buncher (not bought yet, hopefully will piggyback on BNL order)
 - Steerers (copy, modify BNL design)

Why Magnetron Source+RFQ?

- Proven technology
 - BNL retired Cockcroft Waltons in the 1989(!).
 - Has been running reliably with ONE source + RFQ since that time
 - Beam quality and losses are better than Cockcroft Walton (DC versus bunched beam at the start of DTL 1)
 - Magnetron source
 - Dimpled (or round) magnetron source can produce 100mA of H⁻ for 500 us. Our requirement is ~50-60mA for 100 us. **Can run for > 6 months!**
 - Local expertise with slit magnetron source.
 - Leverage HINS programme.

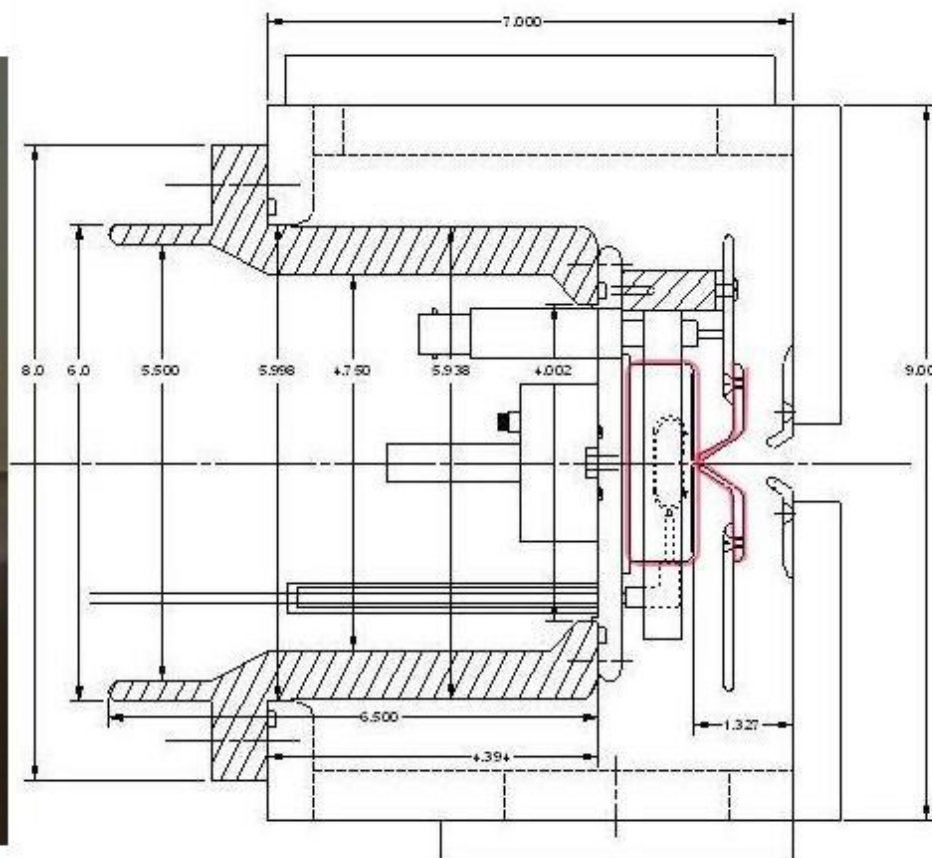
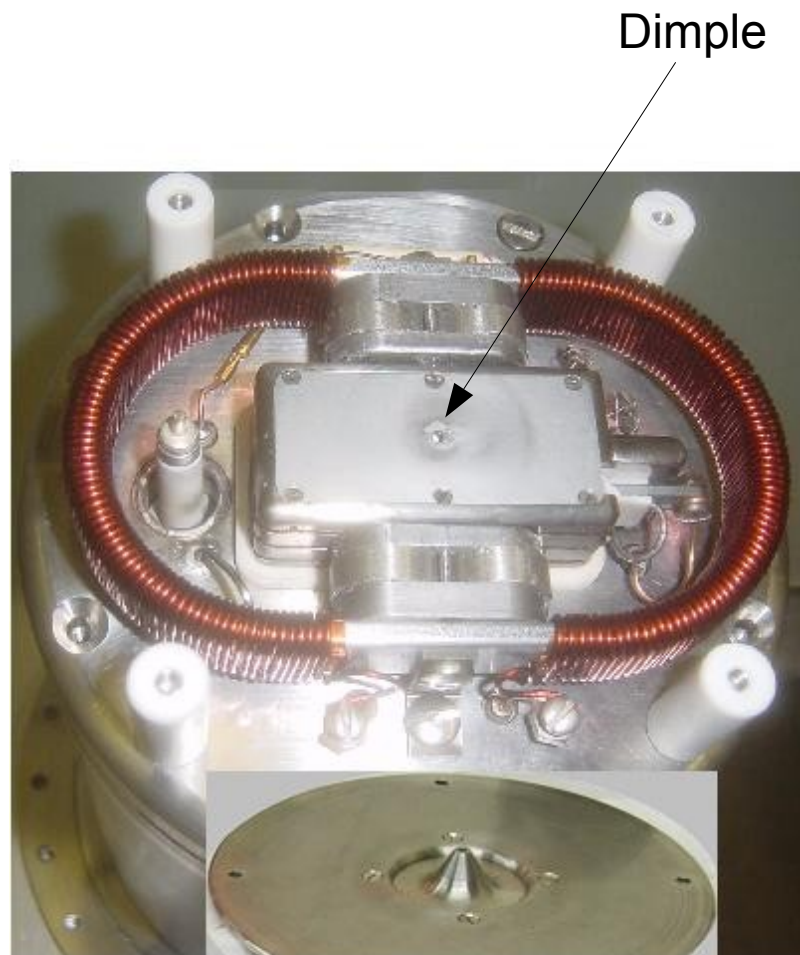
Picture of BNL Pre-Injector



Length of our pre-injector will be about 12-15ft

Source

Round Source

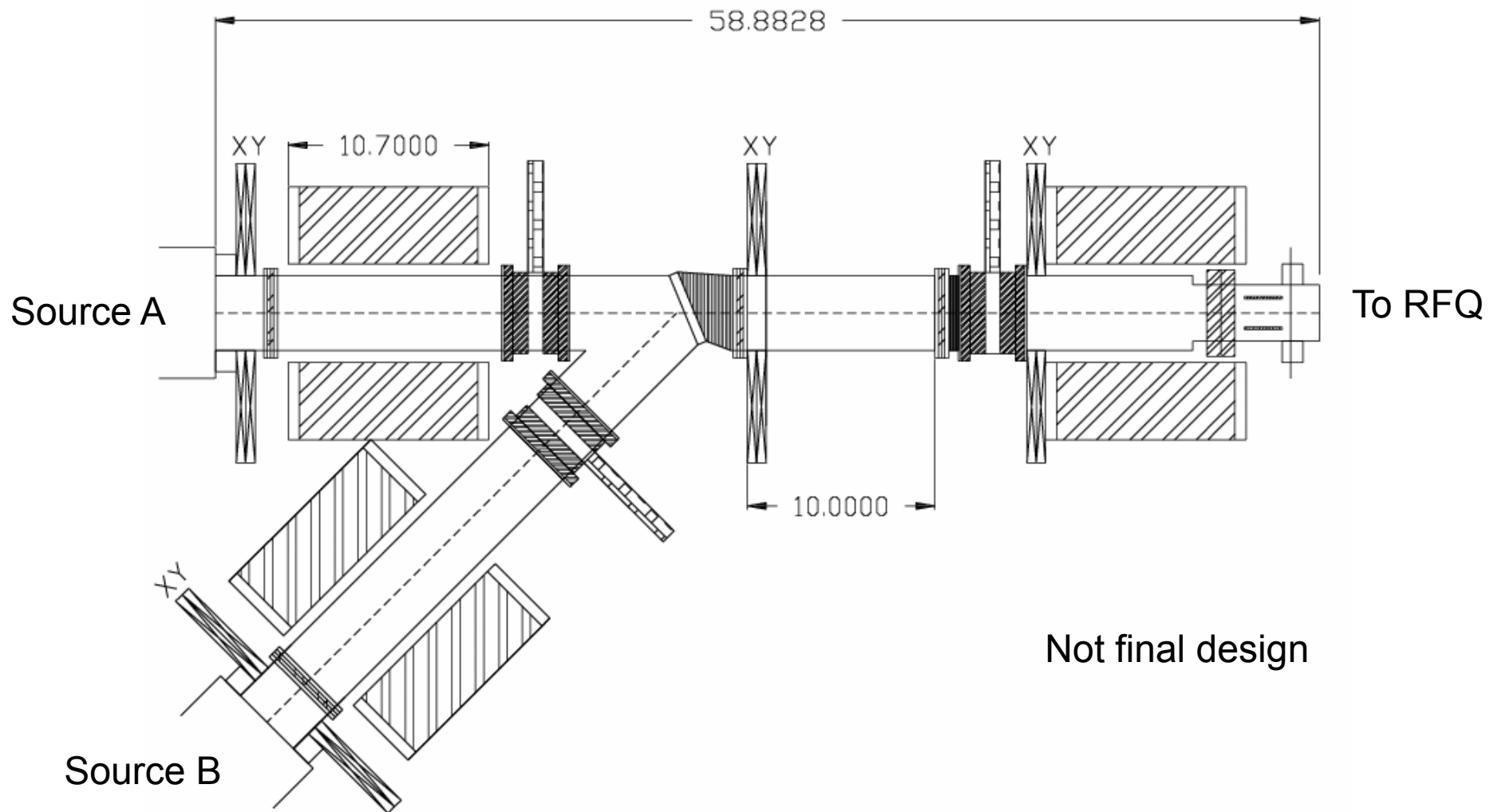


HINS round source very similar to BNL source.
Presently making one. Goal: to show 90-100mA
for 100 us (c.f. BNL 100mA for 500 us)

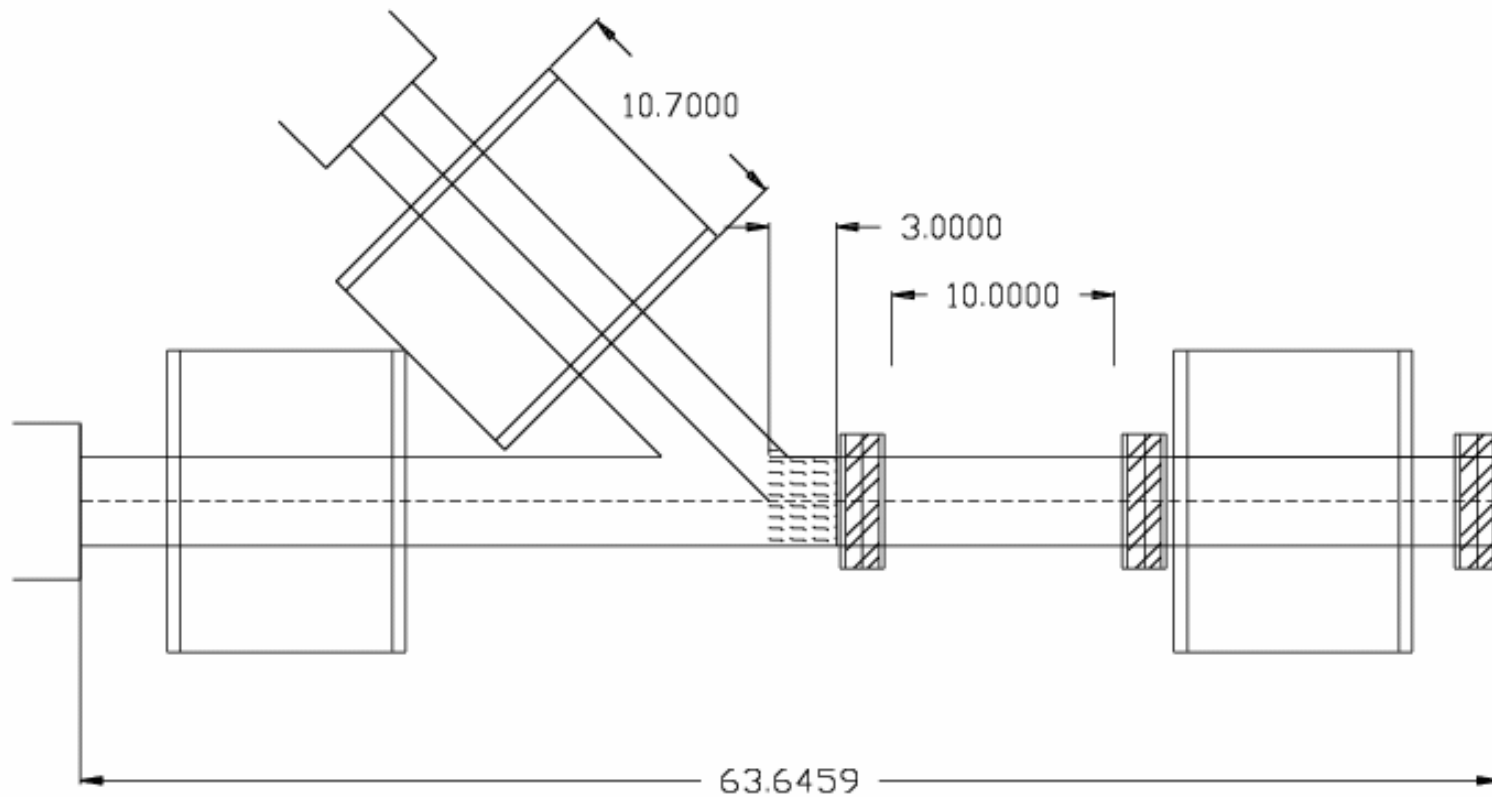
Source

LEBT

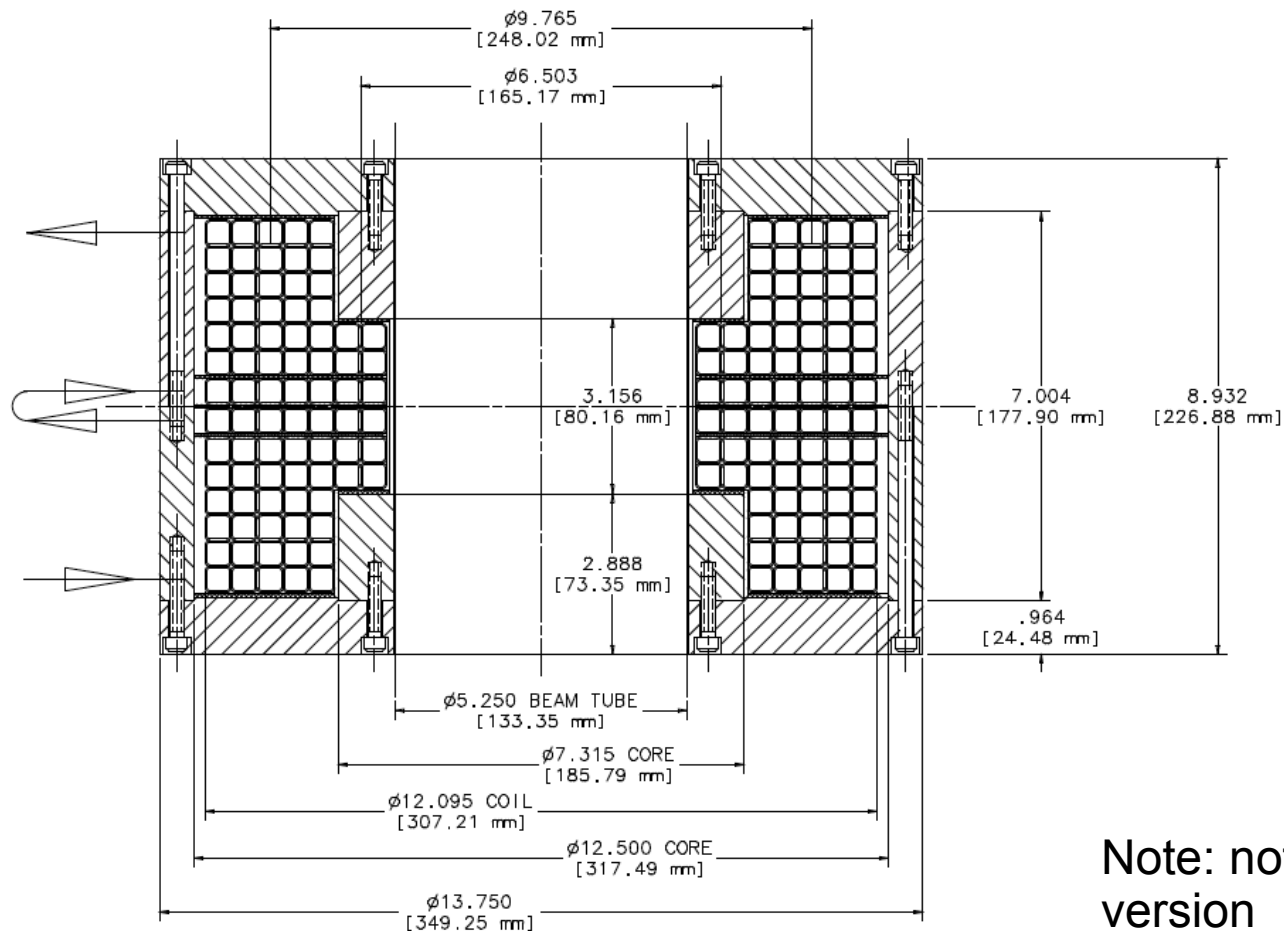
LEBT



Secondary Configuration



Preliminary Solenoid Design



Note: not latest version

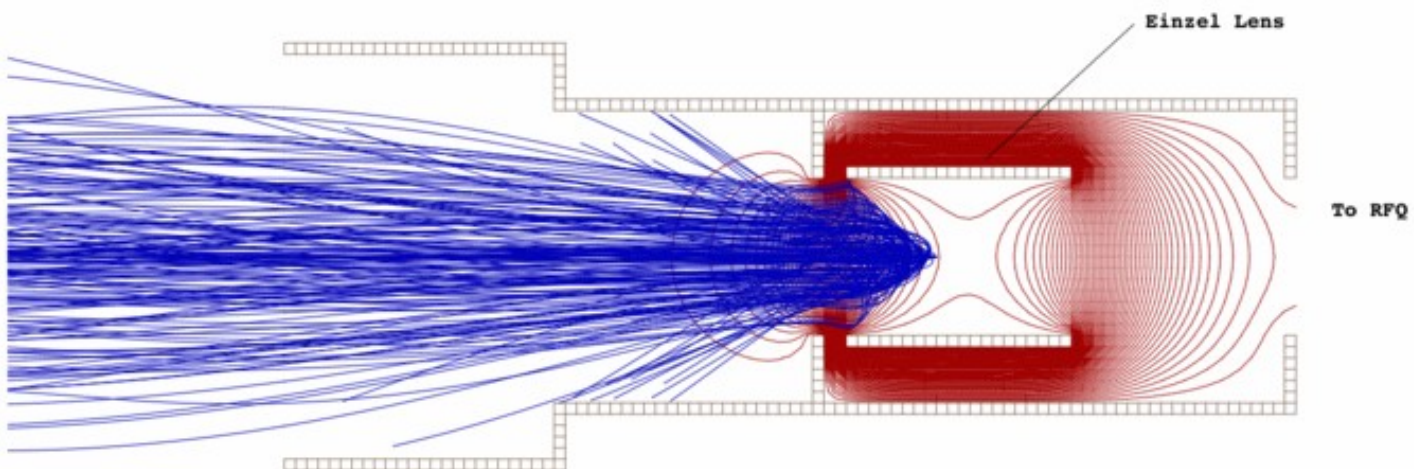
Has been designed.
Going ahead with
prototype. 4.75" bore

VARIANT #3
2 IDENTICAL COILS CONNECTED IN SERIAL
TOTAL NUMBER OF TURNS - 82
NEEDED CONDUCTOT LENGTH - 2 X 105 FT

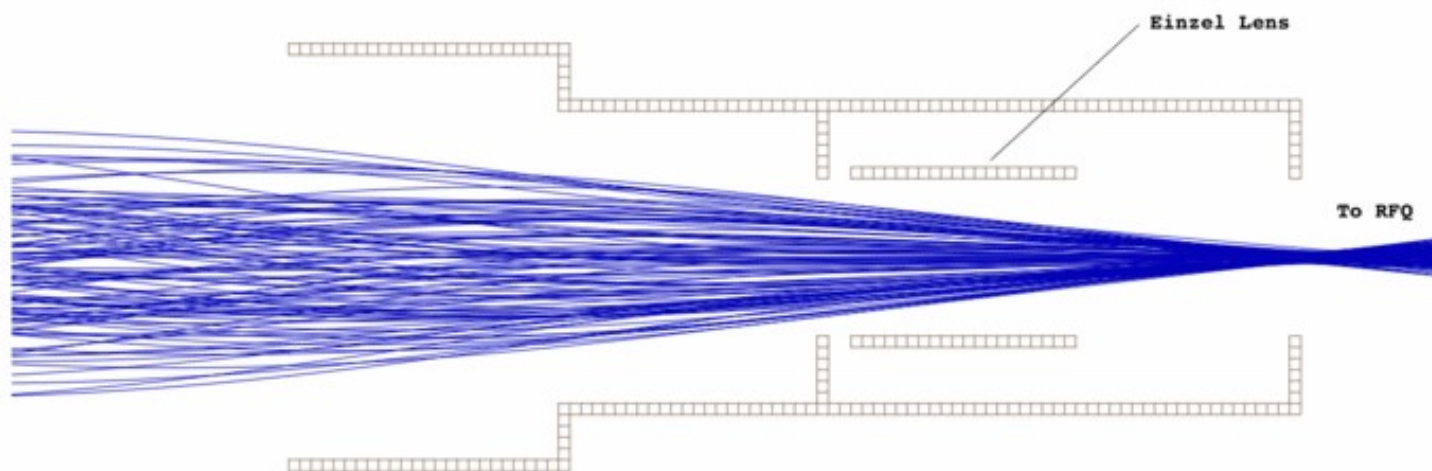
Chopper

Chopper

- Chopper is critical for the pre-injector
 - Electrostatic is usually bad
 - Want to keep H- beam neutralized with Xe+ ions.
 - Our solution (Cut 40us rise time to < 1us?)
 - Use Einzel lens just before RFQ to keep de-neutralization region as small as possible.
 - H- beam is focused near this point, so deneutralization not effective anyway. (Guess)
- Tests with Einzel lens powered to > 36kV has already been done. Looks good!
 - Reverse polarity, pulse it
 - Shoot H- at it
 - Add Xe gas



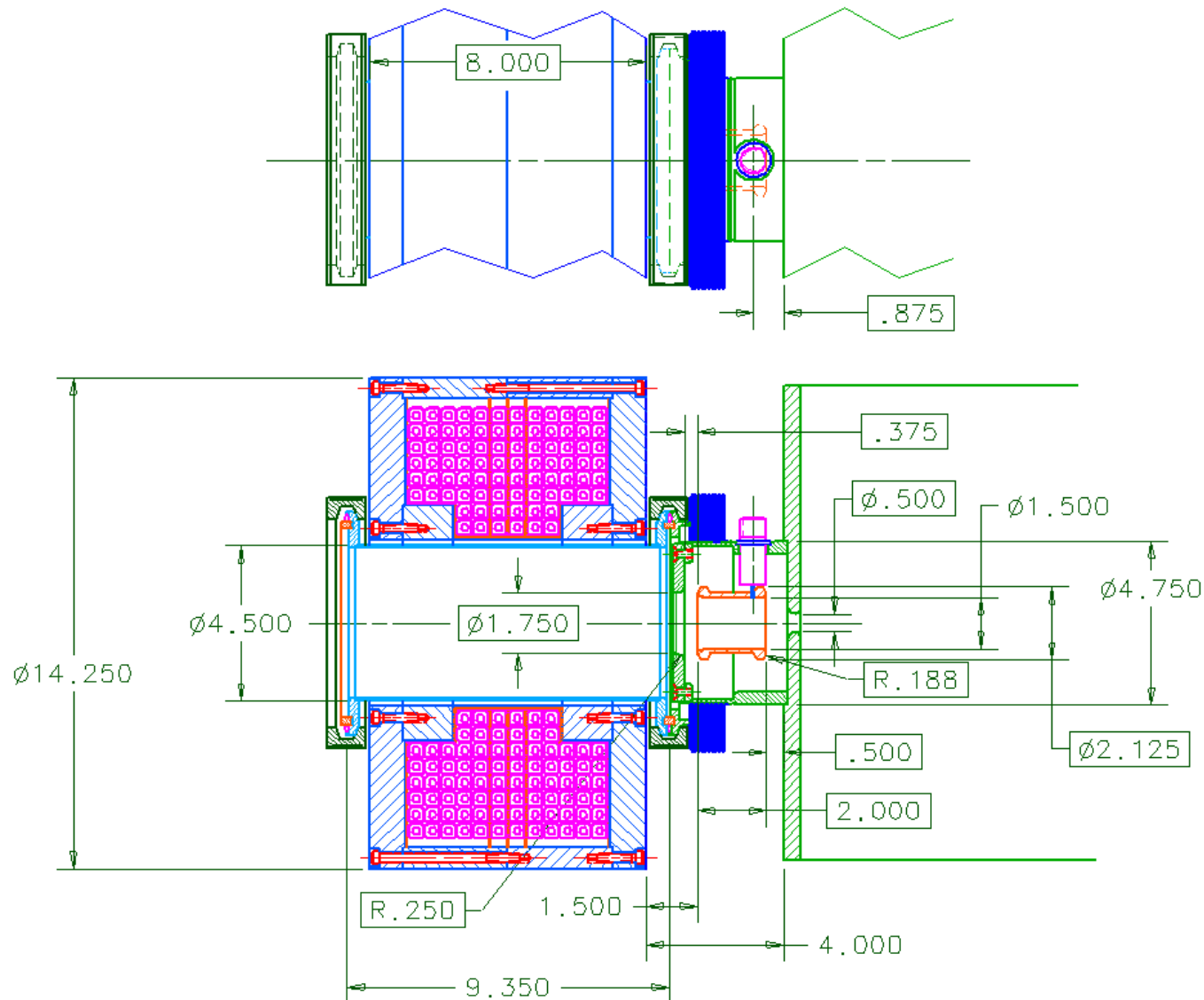
Einzel Lens On at -36.5kV



Einzel Lens Off

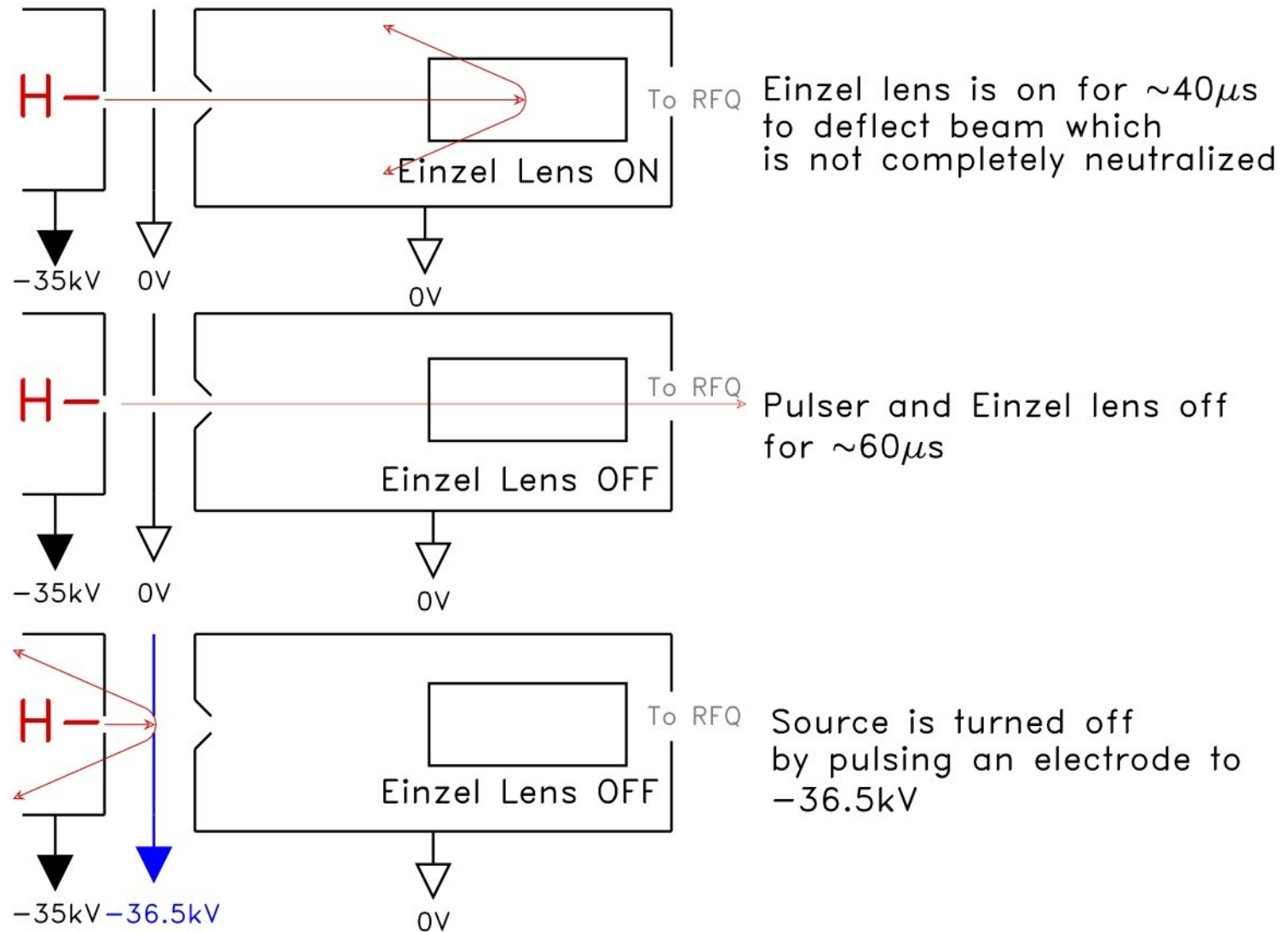
Possible Realization

Designed by A.
Makarov (TD)



DIMENSIONS IN BOXES TO BE VERIFIED

Possible Source Pulser (fallback)



FAST HIGH VOLTAGE TRANSISTOR SWITCHES

These MOSFET switches are designed for general high voltage switching applications such as deflection and acceleration grid drivers and electrical test equipment. The switching modules incorporate all features of the well known HTS switch family: Easy handling, high reliability, low jitter and reproducible switching behaviour. The HTS-LC2 series represents the second generation of Behlke low capacitance switches. The HV transient immunity of the HTS-LC2 series has been improved significantly and is now comparable with that of the standard HTS series.

The switch is turned-on by a positive going control signal of 3 to 6 Volts at the control input (pin1). The shielded control cable is terminated by an internal 100 Ohm resistor. The on-time may simply be controlled by the input control pulse width and can range from 200 ns to infinity. The control electronics of the switching module requires an auxiliary supply of +4.75 to +9.0 VDC (pin 3). To ensure a safe off-state of the switch, the auxiliary supply should be permanently present, especially in the case of possible voltage fluctuations or fast transients at the high voltage input.

An interference-proof driver and control circuit provides signal conditioning, auxiliary voltage monitoring, frequency limitation and temperature protection. Any false operating condition (under voltage, over frequency or over temperature) will result in immediate switch deactivation and a TTL compatible fault signal ("L") will be generated at pin 4 of the control plug. All operating conditions (pulse, on, off, fault) are indicated by LED's.

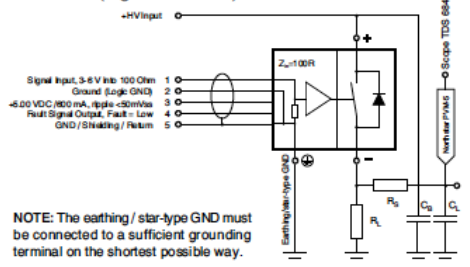
The high frequency burst operation (>10 pulses/100µs) requires the option "HFB" (High Frequency Burst) respectively "I-HFB" (Integrated High Frequency Burst), depending on the number of pulses to be generated. In case of option HFB, external buffer capacitors must be connected to the internal driver circuitry. A continuous high frequency operation above the specified maximum switching frequency requires the option "HFS" (High Frequency Switching). With the help of this option, two external supply voltages can be connected to increase the power capability of the internal switch driver for higher switching frequencies. Those external voltages are +15 V and +380-480 V, depending on switch model. The +5 V auxiliary supply is not required then.

Due to high galvanic isolation, the switches may also simply be operated in floating circuits or in high-side switching applications without any additional isolation transformer or optical coupler. Several housing and cooling options are available to meet individual design requirements. Please refer to product survey "C3 Variable On-Time, Low Coupling Capacitance, MOSFET" or consult BEHLKE for more details.

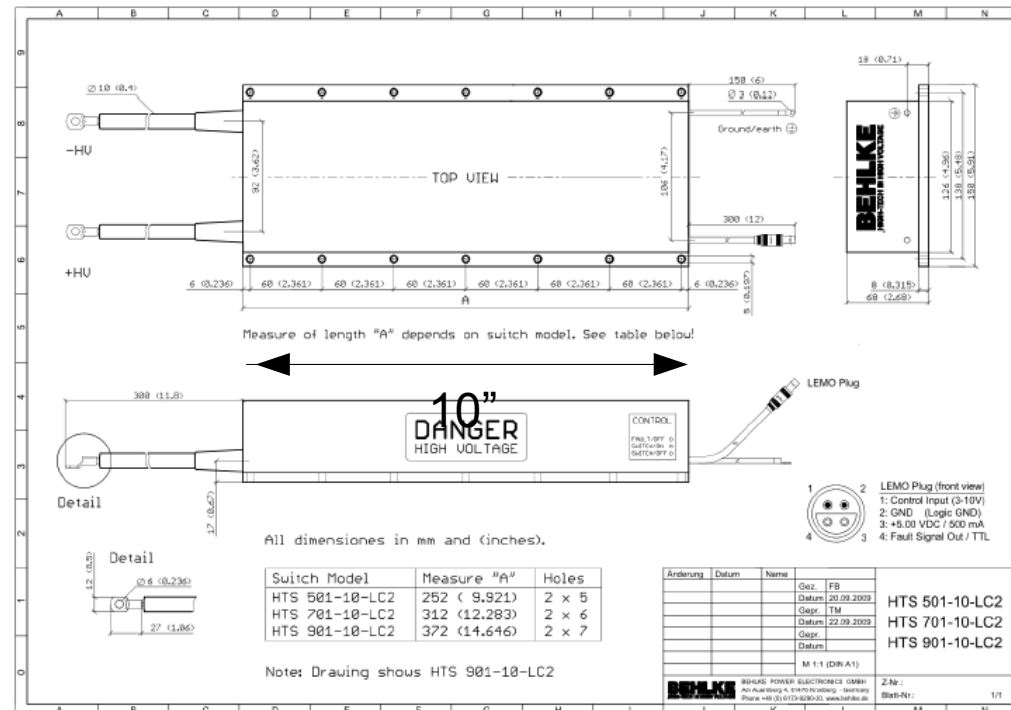
HTS 501-10-LC2 50 kV / 100 A
HTS 701-10-LC2 70 kV / 100 A
HTS 901-10-LC2 90 kV / 100 A



Test Circuit (High-Side Switch)



NOTE: The earthing / star-type GND must be connected to a sufficient grounding terminal on the shortest possible way.



Technical Data

Specification	Symbol	Condition / Comment	HTS 501-10-LC2	HTS 701-10-LC2	HTS 901-10-LC2	Unit
Maximum Operating Voltage	$V_{O(max)}$	$I_{CP} < 50 \mu A$, $T_{case} = 70^\circ C$	50	70	90	kVDC
Maximum Isolation Voltage	V_i	Between HV switch and control input / GND	80	100	120	kVDC
Max. Housing Insulation Voltage	V_{HIS}	Between switch and housing surface, 3 minutes		150		kVDC
Maximum Turn-On Peak Current	$I_{P(max)}$	$T_{case} = 25^\circ C$ $t_p < 200 \mu s$, duty cycle <1% $t_p < 1 ms$, duty cycle <1% $t_p < 10 ms$, duty cycle <1% $t_p < 100 ms$, duty cycle <1%	100	59	36	ADC
Maximum Continuous Load Current	I_L	$T_{case} = 25^\circ C$ $T_{HIS} = 25^\circ C$ Standard model Option DLC - 1.0 / 1.4 / 1.8 % Option DLC - 3.0 / 4.2 / 5.4 %	0.85 4.75 8.25	0.85 4.75 8.25	0.85 4.75 8.25	ADC
Max. Continuous Power Dissipation	$P_{D(max)}$	$T_{case} = 25^\circ C$ $T_{HIS} = 25^\circ C$ Standard model Option DLC - 1.0 / 1.4 / 1.8 % Option DLC - 3.0 / 4.2 / 5.4 %	32 1000 3000	45 1400 4200	58 1800 5400	Watts
Linear Derating		Above $25^\circ C$ Standard model Option DLC - 1.0 / 1.4 / 1.8 % Option DLC - 3.0 / 4.2 / 5.4 %	0.711 22.22 66.66	45 31.11 93.33	1.288 40 120	W/K
Operating Temperature Range	T_O			-40...70		$^\circ C$
Storage Temperature Range	T_S			-40...90		$^\circ C$
Maximum Auxiliary Supply Voltage	$V_{A(max)}$		9			VDC
Permissible Operating Voltage Range	V_O		0...50	0...70	0...90	kVDC
Typical Breakdown Voltage	V_{Br}	CAUTION: V_{Br} is a test parameter only for quality control purposes and is not applicable in normal operation $I_{CP} > 500 \mu A$	53	74	95	kVDC
Typical Off-State Current	I_{off}	$0.8 \times V_O$, $T_{case} = 25^\circ C$		20		μA
Typical Static On-Resistance	$R_{DS(on)}$	$T_{case} = 25^\circ C$ $t_p < 1 \mu s$, duty cycle <1% $0.1 \times I_{P(max)}$ $1.0 \times I_{P(max)}$	20 44	28 62	36 80	Ohm
Typical Turn-On Delay Time	$t_{d(on)}$	Resistive load, $0.1 \times I_{P(max)}$, $0.8 \times V_{O(max)}$, 50-50%		250		ns
Typical Turn-On Rise Time	$t_{r(on)}$	Resistive load, 10-90% $0.1 \times V_{O(max)}$, $0.1 \times I_{P(max)}$ $0.8 \times V_{O(max)}$, $0.1 \times I_{P(max)}$ $0.8 \times V_{O(max)}$, $1.0 \times I_{P(max)}$	12 32 35	14 45 50	15 56 62	ns
Typical Turn-Off Rise Time	$t_{r(off)}$	Resistive load, 10-90% $@ I_{P(max)}$		80		ns
Maximum On-Time	$t_{on(max)}$			Infinitely		
Minimum On-Time	$t_{on(min)}$	$t_{on(min)}$ can be customized. Please consult factory.		250		ns
Maximum Off-Time	$t_{off(max)}$			Infinitely		
Minimum Off-Time	$t_{off(min)}$	$t_{off(min)}$ can be customized. Please consult factory.		250		ns
Typical Turn-On Jitter	$t_{j(on)}$	$V_{AUX} / V_O = 5.00 VDC$		3		ns
Max. Continuous Switching Frequency	$f_{sw(max)}$	$V_{AUX} = 5.00 VDC$, $T_{case} = 25^\circ C$, switch will be turned off, if $t_{P(max)}$ is exceeded Standard Option HFS	1.7	1.2	1	kHz
Maximum Burst Frequency	$f_{B(max)}$	CAUTION: Applications with long testing high frequency bursts may require special cooling measures to prevent overheating of the MOSFET junctions. Please consult factory.		2		MHz
Maximum Number of Pulses / Burst	N	@ $t_{P(max)}$. Note: Option HFB requires external buffer capacitors ($V > 630 VDC$, $C_{ext} \geq 100 nF$ per generated pulse) Standard Option I-HFB Option HFB		10 >100 >10000		Pulses
Coupling Capacitance	C_C	HV side against control side	33	46	60	pF
Natural Capacitance	C_N	Between switch poles	27	20	15	pF
Auxiliary Supply Voltage Range	V_{AUX}	5.00 VDC recommended for best driver efficiency		4.75 - 9.00		VDC
Intrinsic Diode Forward Voltage	V_F	$T_{case} = 25^\circ C$, $I_F = 10 A$	40	57	74	VDC
Diode Reverse Recovery Time	t_{rr}	CAUTION: Intrinsic diodes must not be used in normal operation. Inductive load requires fast free-wheeling diodes (FWD) in parallel to the switch! $I_F = 10 A$		<250		ns
Auxiliary Supply Current	I_{AUX}	$V_{AUX} = 5.00 VDC$, $T_{case} = 25^\circ C$ $0.1 \times I_{P(max)}$ $@ f_{sw(max)}$	250 800	350 800	450 800	mADC
Control Voltage Range	V_{CP}	>5 VDC recommended for best EMC		3 - 10		VDC
Dimensions		Standard housing, without pigtails	252 x 150 x 68	312 x 150 x 68	372 x 150 x 68	mm ³
Weight		Standard housing	3200	4000	4700	g

Rise time 45ns

Technical drawing of a vacuum chamber assembly for a Direct Magnetron Test. The drawing shows a complex arrangement of components including a Pepper-Pot Emittance Probe, Emittance Scanner, Faraday Collector, Collector Repeller, Quartz Image Plate, and Einzel Lens. Dimensions are provided in inches, and various parts are labeled with callouts. A red box highlights the central region containing the Einzel Lens and surrounding structures. The drawing is dated 8/29/2006 and attributed to Chuck Schmidt and Doug Moehs.

Direct Magnetron Test
8/29/2006
Chuck Schmidt, Doug Moehs

Source

Direct Magnetron Test
8/29/2006
Chuck Schmidt, Doug Moehs

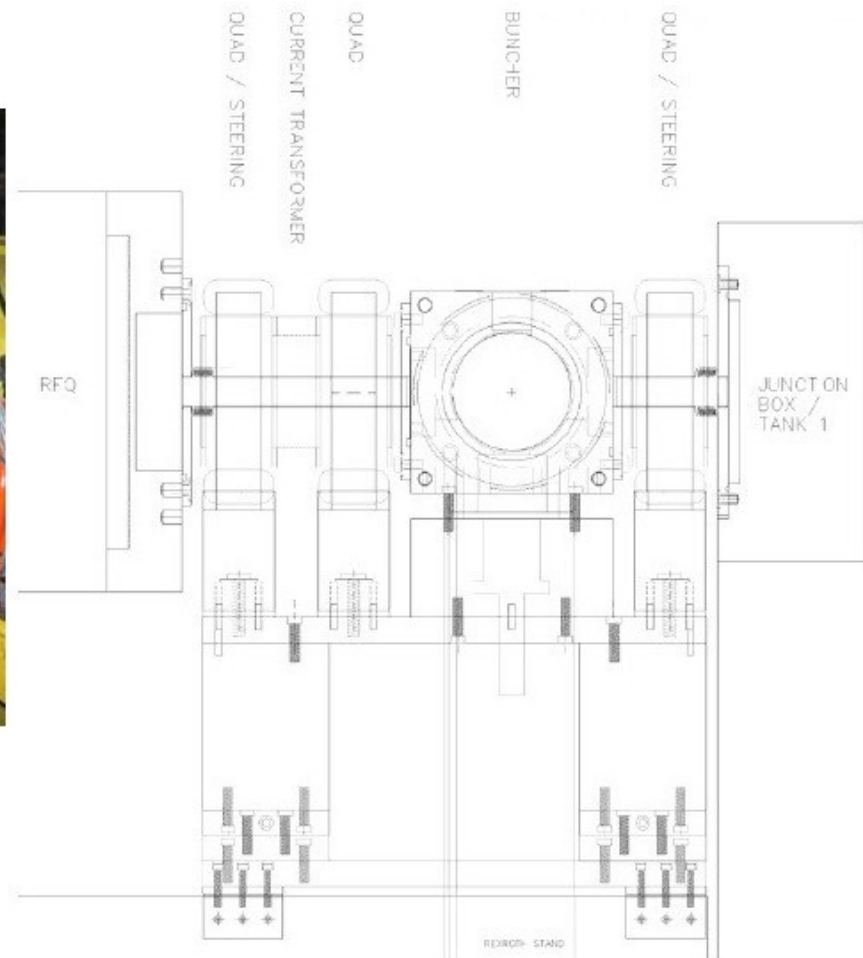
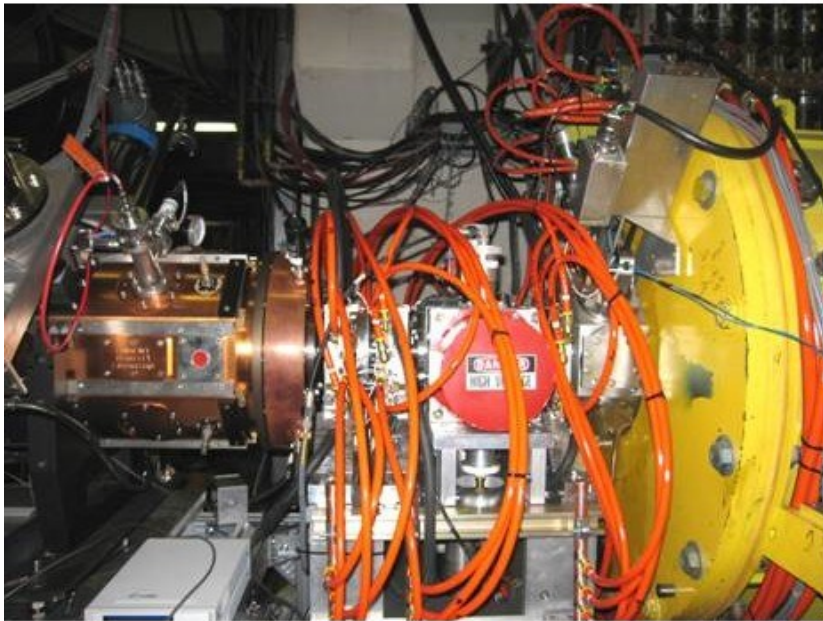
RFQ

Some RFQ Params

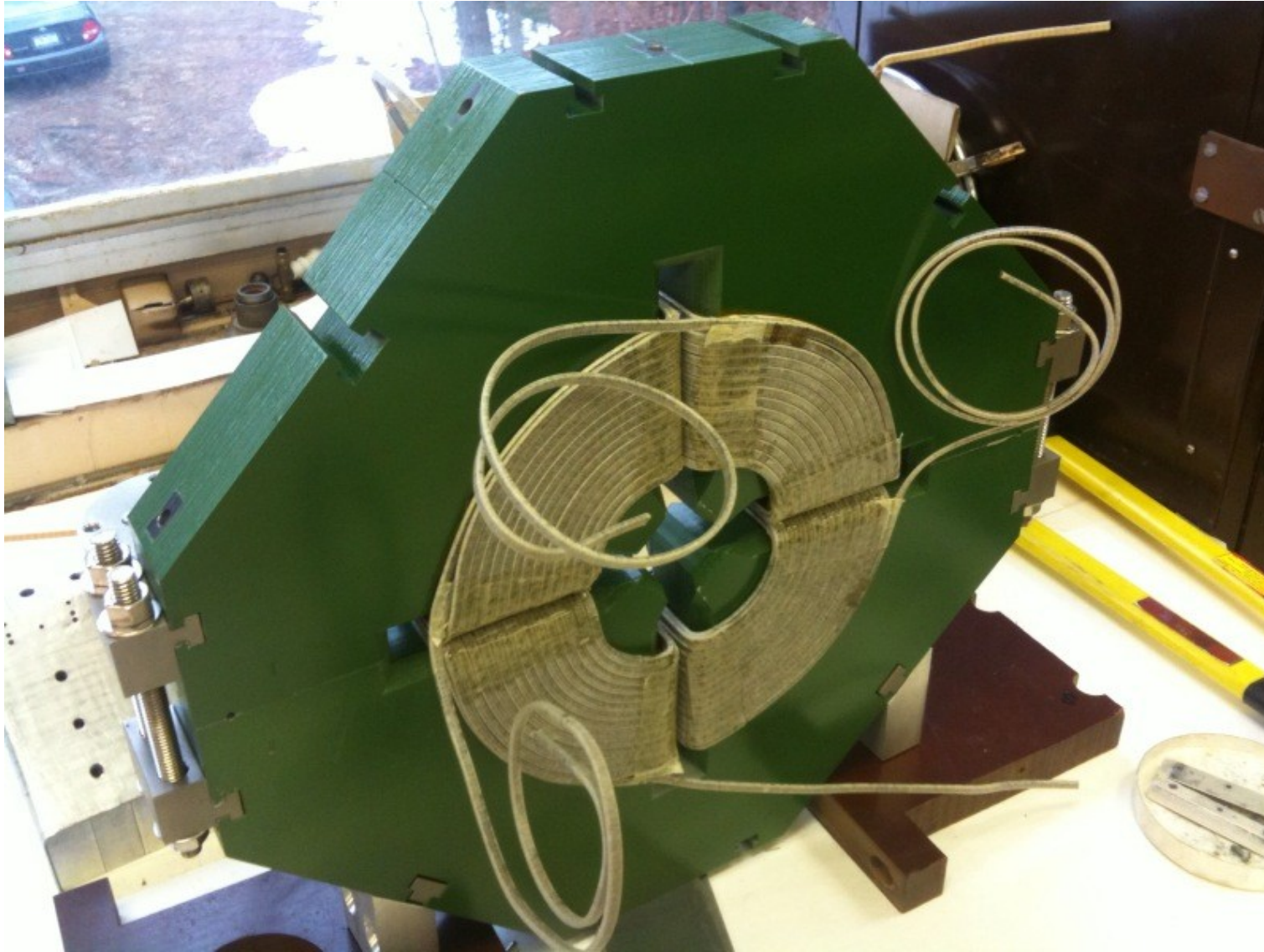
- Input energy: 35keV H-
- Output energy: 750keV
- Frequency: 200MHz
- Input current < 60mA
- > 97% capture efficiency
- 1.2 to 1.6m long
- ~100kW pulsed.

MEBT

MEBT will be a copy of BNL's MEBT



New BNL Quad



65 T/m at 300A.
4.5 cm long.

Requirement is 45
T/m

What needs to be done?

Work

- Show that round source can produce $> 90\text{mA}$ at $100\mu\text{s}$ pulse length.
 - Check reliability claims
- Finish testing chopper at 36kV pulsed.
 - Design and build 36kV chopper power supply, PFN.
 - Can Einzel lens be the ONLY chopper?
- Power supply for RFQ, Buncher, Quads and Solenoids.
- Instrumentation
 - Wires, toroids.
- Test stand for RFQ for validation tests
 - Borrow instrumentation from HINS? Get Vic Scarpine involved.

**Complete installation in 2011-2012
shutdown!!!!**